

FS70UM-2

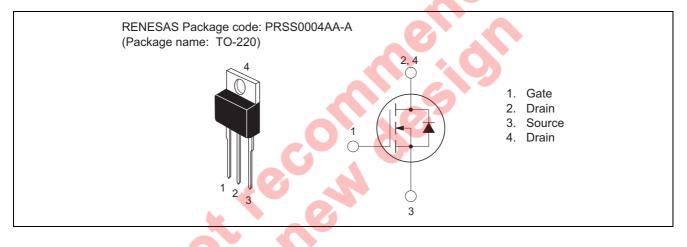
High-Speed Switching Use Nch Power MOS FET

REJ03G1434-0200 (Previous: MEJ02G0108-0101) Rev.2.00 Aug 07, 2006

Features

- Drive voltage : 10 V
- V_{DSS} : 100 V
- $r_{DS(ON)(max)}: 20 \text{ m}\Omega$
- I_D: 70 A
- Integrated Fast Recovery Diode (TYP.) : 120 ns

Outline



Applications

Motor control, Lamp control, Solenoid control, DC-DC converters, etc.

Maximum Ratings

				$(Tc = 25^{\circ}C)$
Parameter	Symbol	Ratings	Unit	Conditions
Drain-source voltage	V _{DSS}	100	V	$V_{GS} = 0 V$
Gate-source voltage	V _{GSS}	±20	V	$V_{DS} = 0 V$
Drain current	I _D	70	Α	
Drain current (Pulsed)	I _{DM}	280	Α	
Avalanche drain current (Pulsed)	I _{DA}	70	Α	L = 100 μH
Source current	Is	70	Α	
Source current (Pulsed)	I _{SM}	280	Α	
Maximum power dissipation	PD	125	W	
Channel temperature	Tch	- 55 to +150	°C	
Storage temperature	Tstg	- 55 to +150	°C	
Mass	—	2.0	g	Typical value



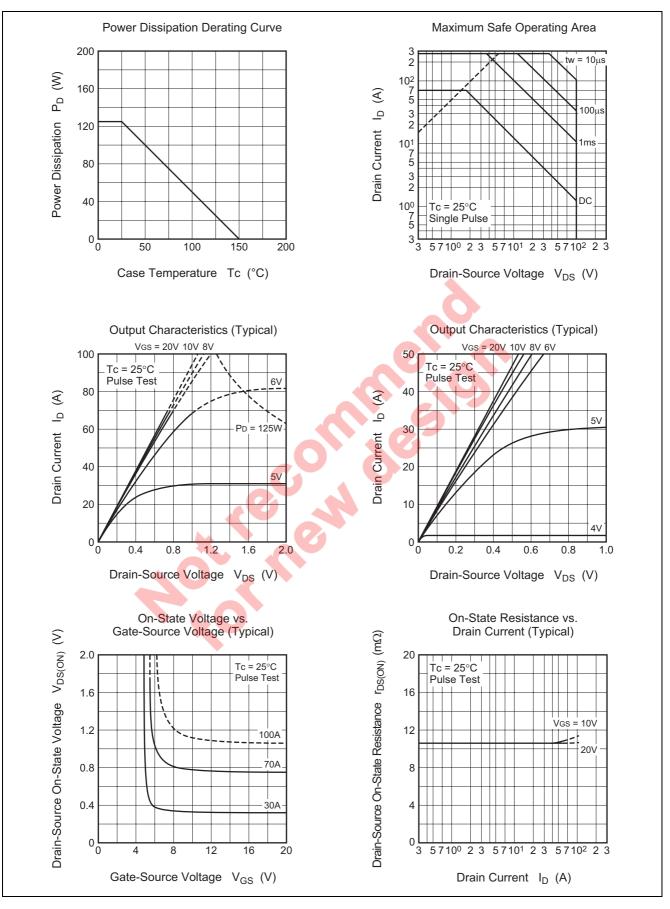
Electrical Characteristics

 $(Tch = 25^{\circ}C)$

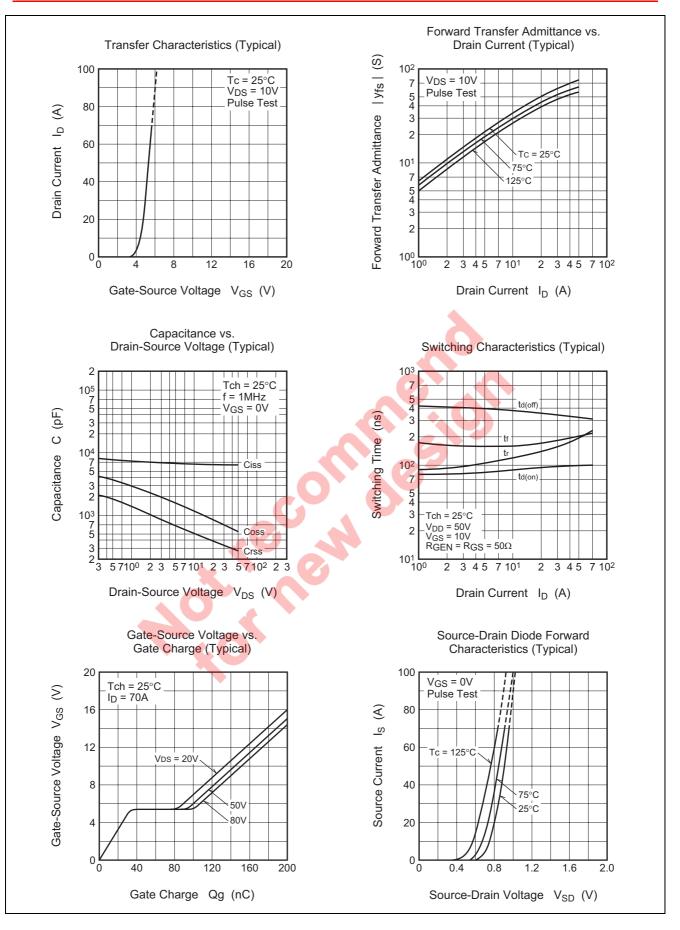
Parameter	Symbol	Min	Тур	Max	Unit	Test Conditions	
Drain-source breakdown voltage	V _{(BR)DSS}	100	—	_	V	$I_{D} = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	
Gate-source leakage current	I _{GSS}	—	—	±0.1	μΑ	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	
Drain-source leakage current	I _{DSS}	—	_	0.1	mA	$V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	
Gate-source threshold voltage	V _{GS(th)}	2.0	3.0	4.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$	
Drain-source on-state resistance	r _{DS(ON)}	—	14	20	mΩ	$I_D = 35 \text{ A}, V_{GS} = 10 \text{ V}$	
Drain-source on-state voltage	V _{DS(ON)}	_	0.49	0.7	V	$I_D = 35 \text{ A}, V_{GS} = 10 \text{ V}$	
Forward transfer admittance	y _{fs}	_	53		S	I _D = 35 A, V _{DS} = 10 V	
Input capacitance	Ciss	_	6540	_	pF	$V_{DS} = 10 V, V_{GS} = 0 V,$	
Output capacitance	Coss	_	1150		pF	f = 1MHz	
Reverse transfer capacitance	Crss	—	500	_	pF		
Turn-on delay time	t _{d(on)}	_	95		ns		
Rise time	tr	_	175		ns		
Turn-off delay time	t _{d(off)}	_	330		ns		
Fall time	t _f	_	190		ns		
Source-drain voltage	V _{SD}	—	1.0	1.5	V	I _S = 35 A, V _{GS} = 0 V	
Thermal resistance	R _{th(ch-c)}	_	—	1.00	°C/W	Channel to case	
Reverse recovery time	t _{rr}		120		ns	$J_{s} = 70 \text{ A}, d_{is}/d_{t} = -100 \text{ A}/\mu s$	



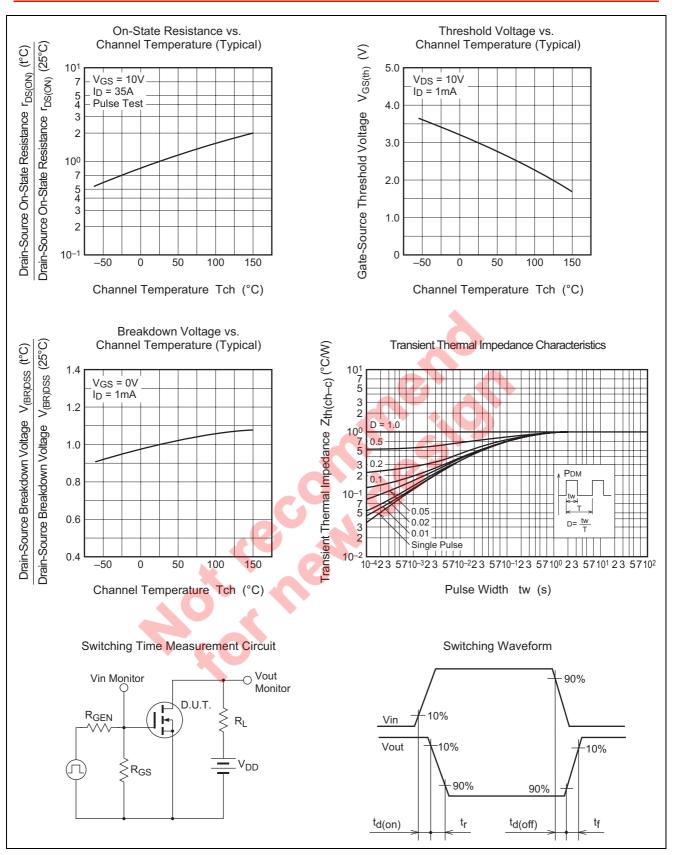
Performance Curves



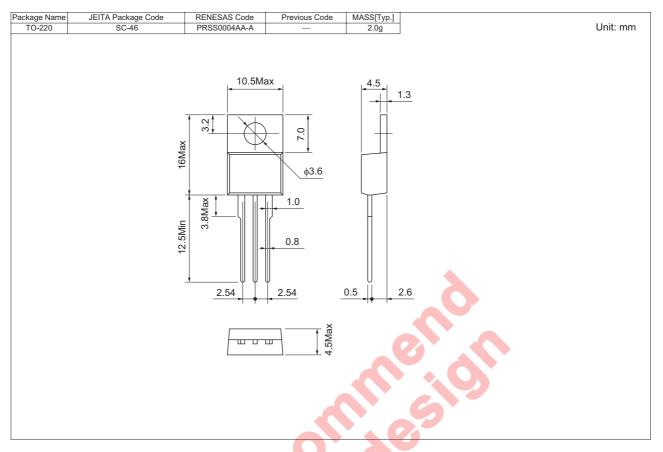








Package Dimensions



Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Straight type	Static electricity prevention bag	100	Type name	FS70UM-2
Lead form	Plastic Magazine (Tube)	50	Type name – Lead forming code	FS70UM-2-A8

Note : Please confirm the specification about the shipping in detail.

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